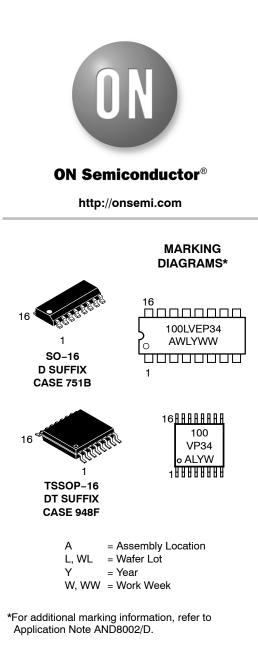
2.5V / 3.3V ECL ÷2, ÷4, ÷8 Clock Generation Chip

The MC100LVEP34 is a low skew $\div 2, \div 4, \div 8$ clock generation chip designed explicitly for low skew clock generation applications. The internal dividers are synchronous to each other, therefore, the common output edges are all precisely aligned. The V_{BB} pin, an internally generated voltage supply, is available to this device only. For single–ended input conditions, the unused differential input is connected to V_{BB} as a switching reference voltage. V_{BB} may also rebias AC coupled inputs. When used, decouple V_{BB} and V_{CC} via a 0.01 µF capacitor and limit current sourcing or sinking to 0.5 mA. When not used, V_{BB} should be left open.

The common enable (\overline{EN}) is synchronous so that the internal dividers will only be enabled/disabled when the internal clock is already in the LOW state. This avoids any chance of generating a runt clock pulse on the internal clock when the device is enabled/disabled as can happen with an asynchronous control. An internal runt pulse could lead to losing synchronization between the internal divider stages. The internal enable flip-flop is clocked on the falling edge of the input clock; therefore, all associated specification limits are referenced to the negative edge of the clock input.

Upon start-up, the internal flip-flops will attain a random state; the master reset (MR) input allows for the synchronization of the internal dividers, as well as multiple LVEP34s in a system. Single-ended CLK input operation is limited to a $V_{CC} \ge 3.0$ V in PECL mode, or $V_{EE} \le -3.0$ V in NECL mode.

- 35 ps Output-to-Output Skew
- Synchronous Enable/Disable
- Master Reset for Synchronization
- The 100 Series Contains Temperature Compensation.
- PECL Mode Operating Range: $V_{CC} = 2.375$ V to 3.8 V with $V_{EE} = 0$ V
- NECL Mode Operating Range: V_{CC} = 0 V with V_{EE} = -2.375 V to -3.8 V
- Open Input Default State
- LVDS Input Compatible
- Pb-Free Packages are Available*

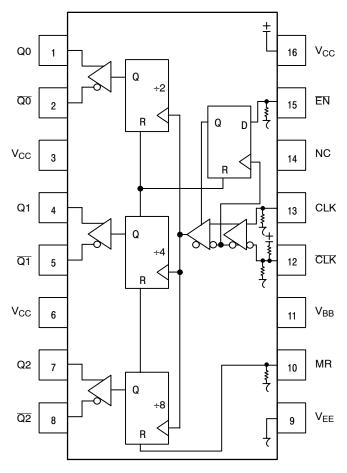


ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 8 of this data sheet.

Semiconductor Components Industries, LLC, 2005
 February, 2005 – Rev. 7

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



Warning: All V_{CC} and V_{EE} pins must be externally connected to Power Supply to guarantee proper operation.

Figure 1. 16–Lead Pinout	(Top View) and Logic Diagram
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Table 1. PIN DESCRIPTION

Pin	Function
CLK*, CLK**	ECL Diff Clock Inputs
EN*	ECL Sync Enable
MR*	ECL Master Reset
Q0, <u>Q0</u>	ECL Diff ÷2 Outputs
Q1, <u>Q1</u>	ECL Diff ÷4 Outputs
Q2, <u>Q2</u>	ECL Diff ÷8 Outputs
V _{BB}	Reference Voltage Output
V _{CC}	Positive Supply
V _{EE}	Negative Supply
NC	No Connect

* Pins will default LOW when left open. **Pins will default to V_{CC}/2 when left open.

Table 2. FUNCTION TABLE

CLK	EN	MR	FUNCTION
Z ZZ X	LHX		Divide Hold Q _{0–3} Reset Q _{0–3}

Z = Low-to-High Transition ZZ = High-to-Low Transition

Table 3. ATTRIBUTES

Characteris	Value	
Internal Input Pulldown Resistor	75 kΩ	
Internal Input Pullup Resistor		37.5 kΩ
ESD Protection	> 2 kV > 200 V > 2 kV	
Moisture Sensitivity, Indefinite Time (Dut of Drypack (Note 1)	Level 1
Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-O @ 0.125 in
Transistor Count		210 Devices
Meets or exceeds JEDEC Spec EIA/	JESD78 IC Latchup Test	

1. For additional Moisture Sensitivity information, refer to Application Note AND8003/D.

Table 4. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V _{CC}	PECL Mode Power Supply	V _{EE} = 0 V		6	V
V_{EE}	NECL Mode Power Supply	V _{CC} = 0 V		-6	V
VI	PECL Mode Input Voltage NECL Mode Input Voltage	V _{EE} = 0 V V _{CC} = 0 V	$\begin{array}{c} V_{I} \leq V_{CC} \\ V_{I} \geq V_{EE} \end{array}$	6 -6	V V
l _{out}	Output Current	Continuous Surge		50 100	mA mA
I _{BB}	V _{BB} Sink/Source			± 0.5	mA
T _A Operating Temperature Range				-40 to +85	°C
T _{stg}	Storage Temperature Range			-65 to +150	°C
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	SOIC-16 SOIC-16	100 60	°C/W °C/W
θ_{JC}	Thermal Resistance (Junction-to-Case)	Standard Board	SOIC-16	33 to 36	°C/W
θ _{JA} Thermal Resistance (Junction-to-Ambient)		0 lfpm 500 lfpm	TSSOP-16 TSSOP-16	138 108	°C/W °C/W
θ_{JC}	Thermal Resistance (Junction-to-Case)	Standard Board	TSSOP-16	33 to 36	°C/W
T _{sol}	Wave Solder	<2 to 3 sec @ 248°C		265	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

			−40°C			25°C				85°C		
Symbol	Characteristic		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{EE}	Power Supply Current		40	50	60	40	50	60	42	52	62	mA
V _{OH}	Output HIGH Voltage (Note 3)		1355	1480	1605	1355	1480	1605	1355	1480	1605	mV
V _{OL}	Output LOW Voltage (Note 3)		555	680	900	555	680	900	555	680	900	mV
V _{IH}	Input HIGH Voltage (Single-Ended) (Note 4)		1335		1620	1335		1620	1275		1620	mV
V _{IL}	Input LOW Voltage (Single-Ended) (Note 4)		555		900	555		900	555		900	mV
V _{IHCMR}	Input HIGH Voltage Common Mode Range (Differential) (Note 4, Note 5)				3.3	1.2		3.3	1.2		3.3	V
I _{IH}	Input HIGH Current				150			150			150	μA
IIL	Input LOW Current	D D	0.5 -150			0.5 -150			0.5 -150			μA

Table 5. 100EP DC CHARACTERISTICS, PECL V_{CC} = 2.5 V, V_{EE} = 0 V (Note 2)

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

2. Input and output parameters vary 1:1 with V_{CC} .

All loading with 50 Ω to V_{CC} - 2.0 V.
 Do not use V_{BB} at V_{CC} < 3.0 V. Single–Ended input CLK pin operation is limited to V_{CC} ≥ 3.0 V in PECL mode.
 V_{IHCMR} min varies 1:1 with V_{EE}, V_{IHCMR} max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

MC100I VFP34

			-40°C			25°C						
Symbol	Characteristic		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{EE}	Power Supply Current		40	50	60	40	50	60	42	52	62	mA
V _{OH}	Output HIGH Voltage (Note 7)		2155	2280	2405	2155	2280	2405	2155	2280	2405	mV
V _{OL}	Output LOW Voltage (Note 7)		1355	1570	1700	1355	1570	1700	1355	1570	1700	mV
V _{IH}	Input HIGH Voltage (Single-Ended)		2075		2420	2075		2420	2075		2420	mV
V _{IL}	Input LOW Voltage (Single-Ended)		1355		1700	1355		1700	1355		1700	mV
V_{BB}	Output Voltage Reference (Note 8)		1775	1875	1975	1775	1875	1975	1775	1875	1975	mV
V _{IHCMR}	Input HIGH Voltage Common Mode Range (Differential) (Note 9)		1.2		3.3	1.2		3.3	1.2		3.3	V
I _{IH}	Input HIGH Current				150			150			150	μΑ
IIL	Input LOW Current	D D	0.5 -150			0.5 -150			0.5 -150			μA

Table 6. 100EP DC CHARACTERISTICS, PECL V_{CC} = 3.3 V, V_{EE} = 0 V (Note 6)

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

6. Input and output parameters vary 1:1 with V_{CC}. V_{EE} can vary +0.925 V to –0.5 V.

7. All loading with 50 Ω to V_{CC} – 2.0 V.

8. Single-Ended input CLK pin operation is limited to V_{CC} \geq 3.0 V in PECL mode.

9. VIHCMR min varies 1:1 with VEE, VIHCMR max varies 1:1 with VCC. The VIHCMR range is referenced to the most positive side of the differential input signal.

			-40°C		25°C						
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{EE}	Power Supply Current	40	50	60	40	50	60	42	52	62	mA
V _{OH}	Output HIGH Voltage (Note 11)	-1145	-1020	-895	-1145	-1020	-895	-1145	-1020	-895	mV
V _{OL}	Output LOW Voltage (Note 11)	-1945	-1700	-1600	-1945	-1700	-1600	-1945	-1700	-1600	mV
V _{IH}	Input HIGH Voltage (Single-Ended)	-1225		-880	-1225		-880	-1225		-880	mV
V _{IL}	Input LOW Voltage (Single-Ended)	-1945		-1600	-1945		-1600	-1945		-1600	mV
V_{BB}	Output Voltage Reference (Note 12)	-1525	-1425	-1325	-1525	-1425	-1325	-1525	-1425	-1325	mV
VIHCMR	Input HIGH Voltage Common Mode Range (Differential) (Note 13)		+1.2	0.0	V _{EE}	+1.2	0.0	V _{EE}	+1.2	0.0	V
I _{IH}	Input HIGH Current			150			150			150	μA
IIL	Input LOW Current D D				0.5 -150			0.5 -150			μA

Table 7. 100EP DC CHARACTERISTICS, NECL $V_{CC} = 0 V$, $V_{EE} = -3.8 V$ to -2.375 V (Note 10)

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

10. Input and output parameters vary 1:1 with V_{CC} .

11. All loading with 50 Ω to V_{CC} – 2.0 V.

12. Single-Ended input CLK pin operation is limited to $V_{EE} \le -3.0 \text{ V}$ in NECL mode. 13. V_{IHCMR} min varies 1:1 with V_{EE} , V_{IHCMR} max varies 1:1 with V_{CC} . The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

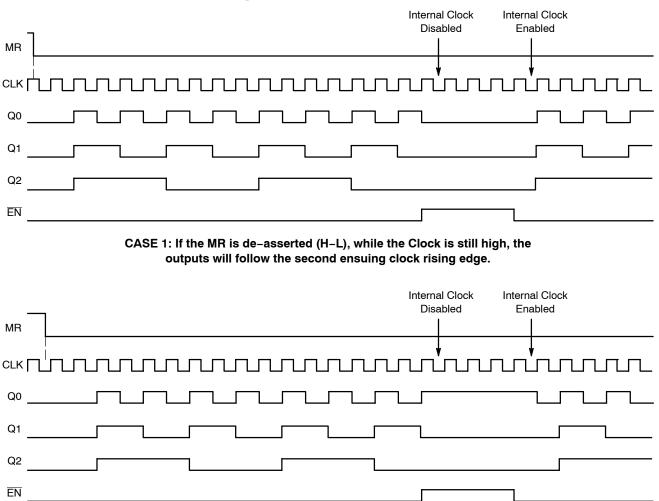
			-40°C		25°C				85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
f _{max}	Maximum Toggle Frequency (See Figure 4. F _{max} /JITTER)	2.8			2.8			2.8			GHz
t _{PLH} t _{PHL}	Propagation CLK to Q0, Q1, Q2 Delay to Output MR to Q	550 500	650 600	750 700	600 550	700 650	800 750	650 600	750 700	850 800	ps
t _{JITTER}	Cycle-to-Cycle Jitter (See Figure 4. F _{max} /JITTER)		< 1			< 1			< 1		ps
t _S	Setup Time EN	150	50		150	50		150	50		ps
t _H	Hold Time EN	200	100		200	100		200	100		ps
t _{RR}	Set/Reset Recovery	300	200		300	200		300	200		ps
V _{PP}	Input Swing (Note 15)	150		1000	150		1000	150		1000	mV
t _r t _f	Output Rise/Fall Times Q (20% – 80%)	90	170	200	100	180	250	120	200	280	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

14. Measured using a 750 mV source, 50% duty cycle clock source. All loading with 50 Ω to V_{CC} – 2.0 V.

15. $V_{PP(min)}$ is minimum input swing for which AC parameters guaranteed. The device has a DC gain of ~40.

There are two distinct functional relationships between the Master Reset and Clock:



CASE 2: If the MR is de-asserted (H–L), after the Clock has transitioned low, the outputs will follow the third ensuing clock rising edge.

Figure 2. Timing Diagrams

The \overline{EN} signal will "freeze" the internal divider flip-flops on the first falling edge of CLK after its assertion. The internal divider flip-flops will maintain their state during the freeze. When \overline{EN} is deasserted (LOW), and after the next falling edge of CLK, then the internal divider flip-flops will "unfreeze" and continue to their next state count with proper phase relationships.

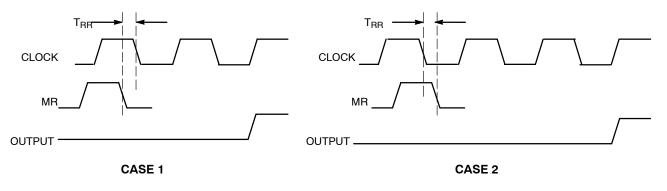


Figure 3. Reset Recovery Time

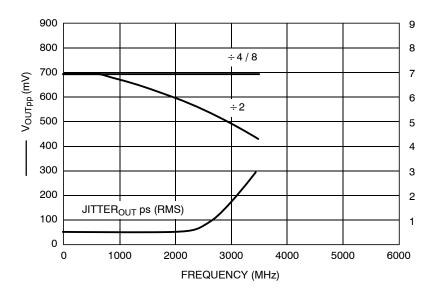


Figure 4. F_{max}/Jitter

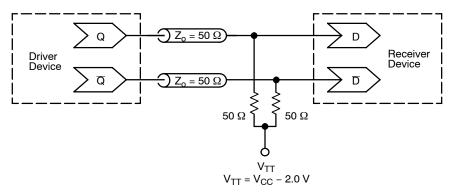


Figure 5. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020/D – Termination of ECL Logic Devices.)

ORDERING INFORMATION

Device	Package	Shipping [†]
MC100LVEP34D	SOIC-16	48 Units / Rail
MC100LVEP34DR2	SOIC-16	2500 / Tape & Reel
MC100LVEP34DT	TSSOP-16*	96 Units / Rail
MC100LVEP34DTR2	TSSOP-16*	2500 / Tape & Reel
MC100LVEP34DTR2G	TSSOP-16 (Pb-Free)	2500 / Tape & Reel

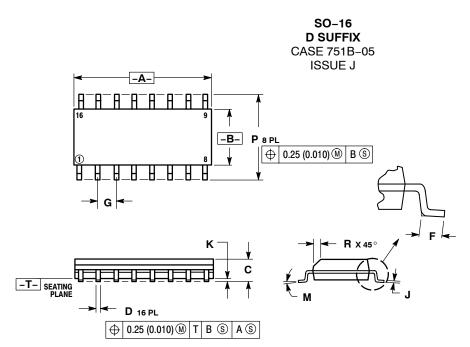
+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*This package is inherently Pb-Free.

Resource Reference of Application Notes

AN1405/D	-	ECL Clock Distribution Techniques			
AN1406/D	-	Designing with PECL (ECL at +5.0 V)			
AN1503/D	-	ECLinPS [™] I/O SPiCE Modeling Kit			
AN1504/D	-	Metastability and the ECLinPS Family			
AN1568/D	-	Interfacing Between LVDS and ECL			
AN1642/D	-	The ECL Translator Guide			
AND8001/D	-	Odd Number Counters Design			
AND8002/D	-	Marking and Date Codes			
AND8020/D	-	Termination of ECL Logic Devices			
AND8066/D	_	Interfacing with ECLinPS			
AND8090/D	_	AC Characteristics of ECL Devices			

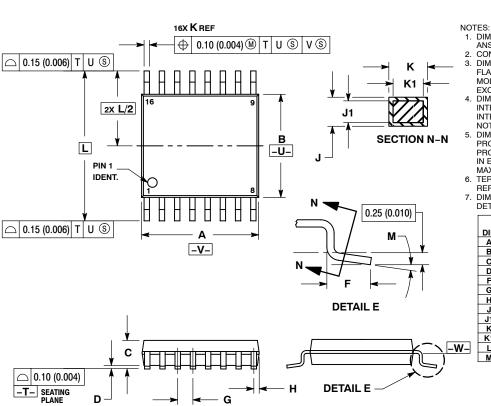
PACKAGE DIMENSIONS



NOTES:
 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
 DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION.
 MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
 DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	9.80	10.00	0.386	0.393	
В	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.054	0.068	
D	0.35	0.49	0.014	0.019	
F	0.40	1.25	0.016	0.049	
G	1.27	BSC	0.050 BSC		
J	0.19	0.25	0.008	0.009	
K	0.10	0.25	0.004	0.009	
М	0 °	7°	0 °	7°	
Р	5.80	6.20	0.229	0.244	
R	0.25	0.50	0.010	0.019	

PACKAGE DIMENSIONS



G

D

TSSOP-16 CASE 948F-01 **ISSUE A**

NOTES:
 DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
 DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
 DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION.
 TOMENSION & LOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION. ALLL BO 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
 TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.

REFERENCE ONLY.
DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	4.90	5.10	0.193	0.200	
В	4.30	4.50	0.169	0.177	
С		1.20		0.047	
D	0.05	0.15	0.002	0.006	
F	0.50	0.75	0.020	0.030	
G	0.65	BSC	0.026 BSC		
Н	0.18	0.28	0.007	0.011	
ſ	0.09	0.20	0.004	0.008	
J1	0.09	0.16	0.004	0.006	
к	0.19	0.30	0.007	0.012	
K1	0.19	0.25	0.007	0.010	
L	6.40		0.252 BSC		
М	0 °	8 °	0 °	8 °	

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